

**Amendments to the Specification:**

Please replace the paragraph beginning at  
with the following rewritten paragraph:

P-23, line 28 SN  
P2121

An important issue in the placement of objects 3 on a substrate is the interconnect of the object 3 to the outside world. There are several options for this which are standard. First it can be done in the standard lithographic way. This is sketched in FIG. 4. In FIG. 4a the object is shown after placement of the object 3 close to a connecting line 6. On top of the object 3 there is a conducting part 7. By standard lithography ~~via's~~ vias 8 are made and the object 3 is connected.